

**APPENDIX- SPECIFICATION  
MARKED TO SHOW CHANGES**

**CROSS-REFERENCE TO RELATED APPLICATIONS**

The present application is a continuation-in-part of U.S. Application No. 09/651,779 (~~attorney docket number 108298515US~~), titled "Methods and Apparatus for Removing Conductive Material From a Microelectronic Substrate," filed August 30, 2000. Additionally, this application is related to; U.S. Application No. 09/887,767 (attorney docket number 108298515US2), titled "Microelectronic Substrate Having Conductive Material with Blunt Cornered Apertures, and Associated Methods for Removing Conductive Material," filed June 21, 2001~~concurrently herewith~~, and U.S. Application No. 09/888,002 (attorney docket number 108298515US3), titled "Methods and Apparatus for Electrically and/or Chemically-Mechanically Removing Conductive Material from a Microelectronic Substrate," filed June 21, 2001~~concurrently herewith~~. All of the U.S. Patent Applications listed above are incorporated herein by reference,~~all of which are incorporated herein in their entireties by reference.~~

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